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(54) Title: DISPENSING PROCESS FOR FABRICATION OF MICROELECTRONIC PACKAGES

(57) Abstract: A microelectronic package including at least one microelectronic die disposed within an opening in a microelectronic package core, wherein a liquid encapsulation material is injected with a dispensing needle within the portions of the opening not occupied by the microelectronic dice. The encapsulation material is cure thereafter. Interconnection layers of dielectric material and conductive traces are then fabricated on the microelectronic die, the encapsulation material, and the microelectronic package core to form the microelectronic package.